

Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceed the OCM data sheet.

Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
 - Class Q Military
 - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)
 - Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.

Features

- Guaranteed to meet full electrical specifications over $T_A = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$
- System frequency up to 100 MHz (10 ns)
- Available in small footprint packages
- Optimized for high-performance 3.3V systems
 - 5V tolerant I/O pins accept 5V, 3.3V, and 2.5V signals — ideal for multi-voltage system interfacing and level shifting
 - Technology: 0.35 μm CMOS process
- Advanced system features
 - In-system programmable enabling higher system reliability through reduced handling and reducing production programming times
 - Superior pin-locking and routability with FastCONNECT™ II switch matrix allowing for multiple design iterations without board re-spins
 - Input hysteresis on all user and boundary-scan pin inputs to reduce noise on input signals
 - Bus-hold circuitry on all user pin inputs which reduces cost associated with pull-up resistors and reduces bus loading
 - Full IEEE Standard 1149.1 boundary-scan (JTAG) for in-system device testing
 - Fast concurrent programming
- Slew rate control on individual outputs for reducing EMI generation

Description

The XC9500XL 3.3V CPLD Automotive IQ product family is targeted for leading-edge, high-performance, low-voltage automotive (-40°C to $+125^{\circ}\text{C}$) applications.

Power Estimation

Power dissipation in CPLDs can vary substantially depending on the system frequency, design application and output loading. To help reduce power dissipation, each macrocell in the XC9500XL device can be configured for low-power mode (from the default high-performance mode). In addition, unused product-terms and macrocells are automatically deactivated by the software to further conserve power.

For a general estimate of I_{CC} , the following equation may be used:

$$I_{CC} \text{ (mA)} = MC_{HP}(0.5) + MC_{LP}(0.3) + MC(0.0045 \text{ mA/MHz}) f$$

where:

MC_{HP} = Macrocells in high-performance (default) mode

MC_{LP} = Macrocells in low-power mode

MC = Total number of macrocells used

f = Clock frequency (MHz)

This calculation is based on typical operating conditions using a pattern of 16-bit up/down counters in each Function Block with no output loading. The actual I_{CC} value varies with the design application and should be verified during normal system operation.

Table 1: XC9500XL Device Family

Device	Macrocells	Usable Gates	Registers	f_{SYSTEM} (MHz)
XC9536XL	36	800	36	100
XC9572XL	72	1,600	72	100

Table 2: XC9500XL Packages and User I/O Pins (not including four dedicated JTAG pins)

Device	VQ44	VQ64	TQ100
XC9536XL	34	36	-
XC9572XL	-	52	72

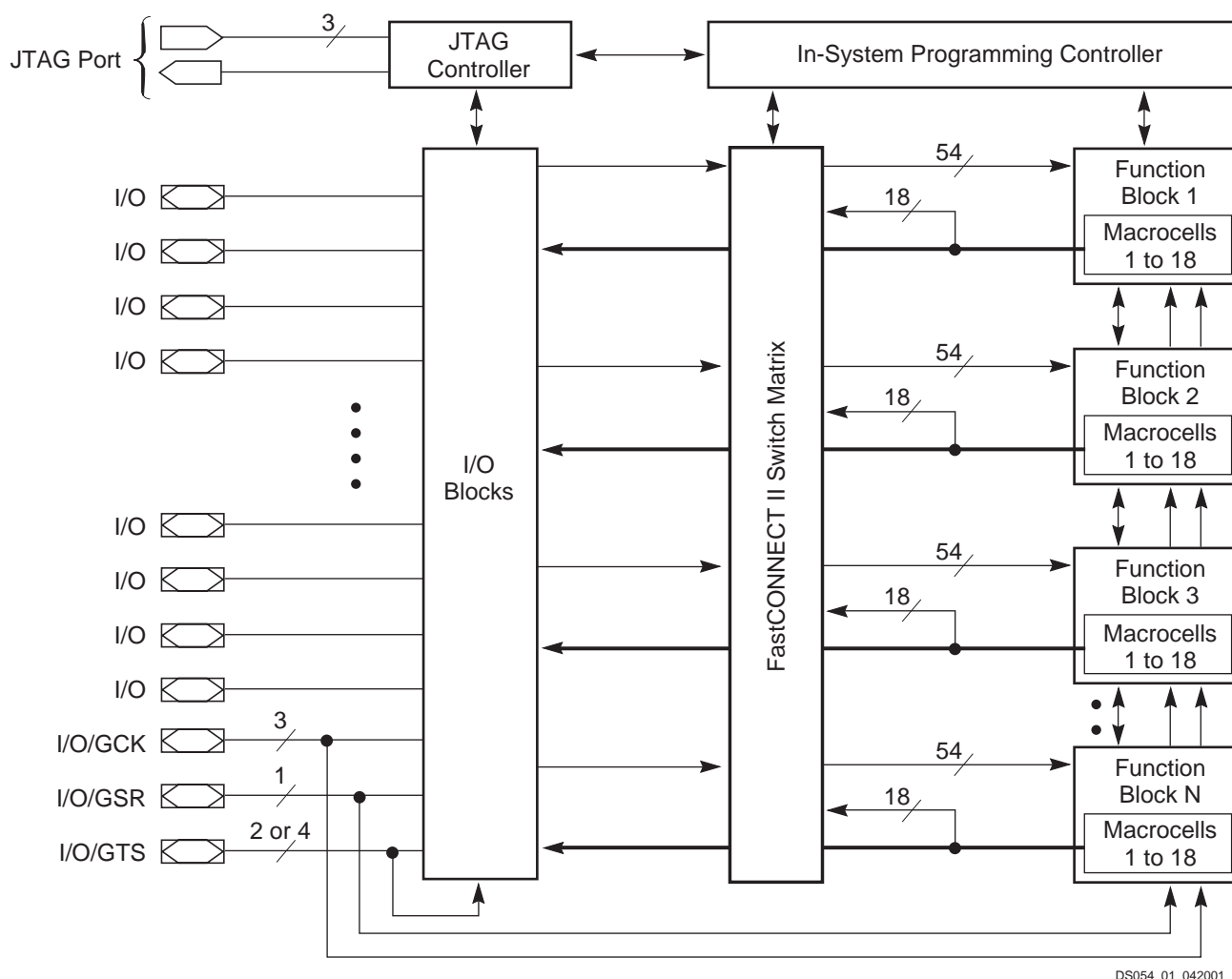


Figure 1: XC9500XL Architecture

Note: Function block outputs (indicated by the bold lines) drive the I/O blocks directly.

Family Overview

The FastFLASH XC9500XL family is a 3.3V CPLD family targeted for high-performance applications in leading-edge communications, computing, and automotive systems, where high device reliability and low power dissipation is important. Each XC9500XL device supports in-system programming (ISP) and the full IEEE 1149.1 (JTAG) boundary-scan, allowing superior debug and design iteration capability for small form-factor packages. The XC9500XL family is designed to work closely with the Xilinx Virtex, Spartan-XL and XC4000XL FPGA families, allowing system designers to partition logic optimally between fast interface circuitry and high-density general purpose logic. As shown in Table 1, logic density of the XC9500XL devices ranges from 800 to 1,600 usable gates with 36 to 72 registers, respectively. Multiple package options and associated I/O capacity are shown in Table 1. The XC9500XL family members are fully pin-compatible, allowing easy design migration

across multiple density options in a given package footprint.

The XC9500XL architectural features address the requirements of in-system programmability. Enhanced pin-locking capability avoids costly board rework. In-system programming throughout the full commercial operating range and a high programming endurance rating provide worry-free reconfigurations of system field upgrades. Extended data retention supports longer and more reliable system operating life.

Advanced system features include output slew rate control and user-programmable ground pins to help reduce system noise. Each user pin is compatible with 5V, 3.3V, and 2.5V inputs, and the outputs may be configured for 3.3V or 2.5V operation. The XC9500XL devices exhibit symmetric full 3.3V output voltage swing to allow balanced rise and fall times.

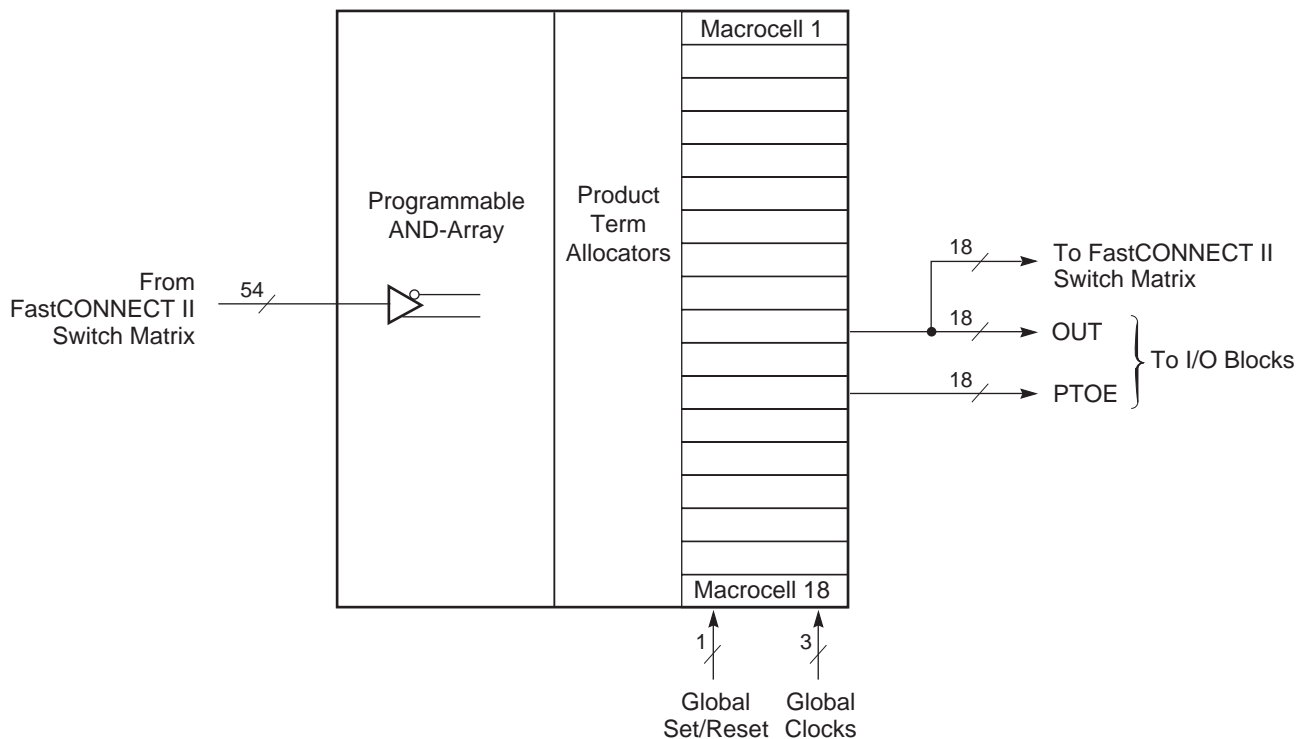
Architecture Description

Each XC9500XL device is a subsystem consisting of multiple Function Blocks (FBs) and I/O Blocks (IOBs) fully interconnected by the FastCONNECT II switch matrix. The IOB provides buffering for device inputs and outputs. Each FB provides programmable logic capability with extra wide 54 inputs and 18 outputs. The FastCONNECT II switch matrix connects all FB outputs and input signals to the FB inputs. For each FB, up to 18 outputs (depending on package pin-count) and associated output enable signals drive directly to the IOBs. See [Figure 1](#)

Function Block

Each Function Block, as shown in [Figure 2](#) is comprised of 18 independent macrocells, each capable of implementing a combinatorial or registered function. The FB also receives global clock, output enable, and set/reset signals. The FB generates 18 outputs that drive the FastCONNECT switch matrix. These 18 outputs and their corresponding output enable signals also drive the IOB.

Logic within the FB is implemented using a sum-of-products representation. Fifty-four inputs provide 108 true and complement signals into the programmable AND-array to form 90 product terms. Any number of these product terms, up to the 90 available, can be allocated to each macrocell by the product term allocator.



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Figure 2: XC9500XL Function Block

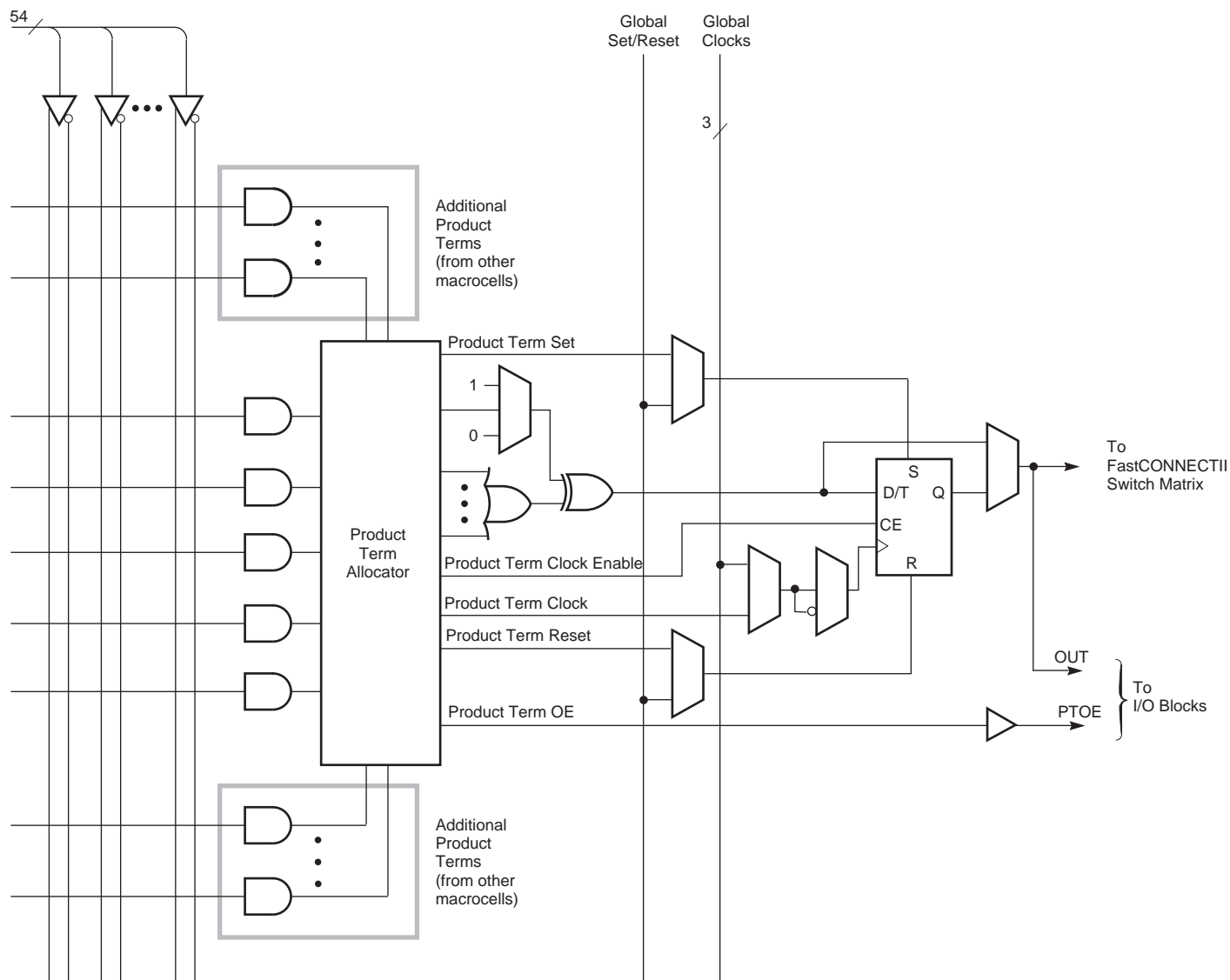
Macrocell

Each XC9500XL macrocell may be individually configured for a combinatorial or registered function. The macrocell and associated FB logic is shown in [Figure 3](#).

Five direct product terms from the AND-array are available for use as primary data inputs (to the OR and XOR gates) to implement combinatorial functions, or as control inputs including clock, clock enable, set/reset, and output enable.

The product term allocator associated with each macrocell selects how the five direct terms are used.

The macrocell register can be configured as a D-type or T-type flip-flop, or it may be bypassed for combinatorial operation. Each register supports both asynchronous set and reset operations. During power-up, all user registers are initialized to the user-defined preload state (default to 0 if unspecified)

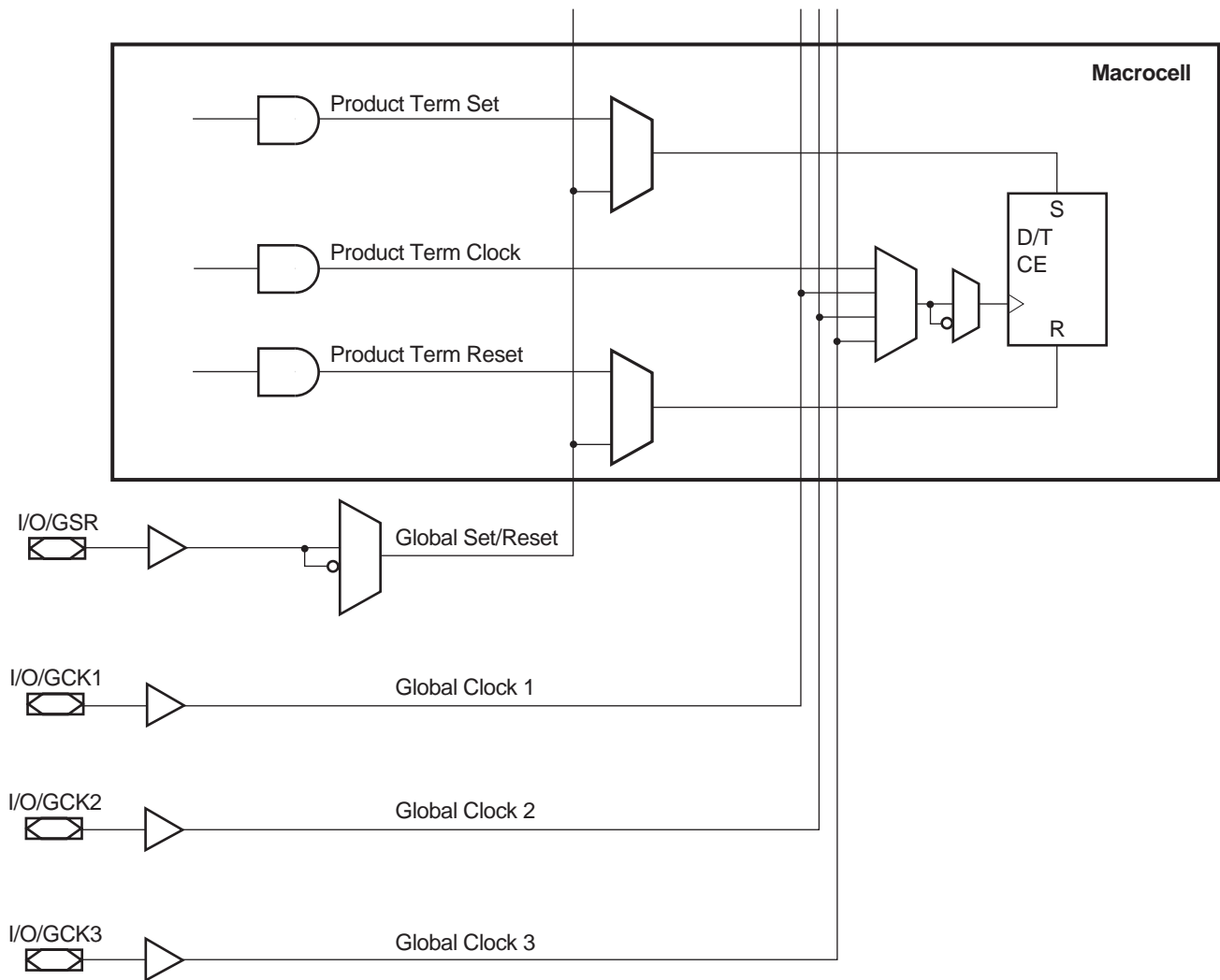


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Figure 3: XC9500XL Macrocell Within Function Block

All global control signals are available to each individual macrocell, including clock, set/reset, and output enable signals. As shown in [Figure 4](#), the macrocell register clock originates from either of three global clocks or a product

term clock. Both true and complement polarities of the selected clock source can be used within each macrocell. A GSR input is also provided to allow user registers to be set to a user-defined state.

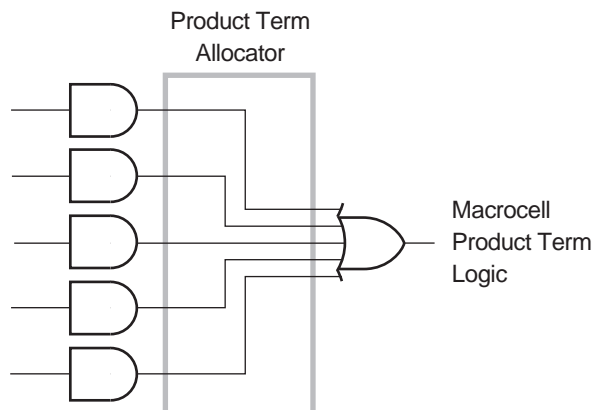


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Figure 4: Macrocell Clock and Set/Reset Capability

Product Term Allocator

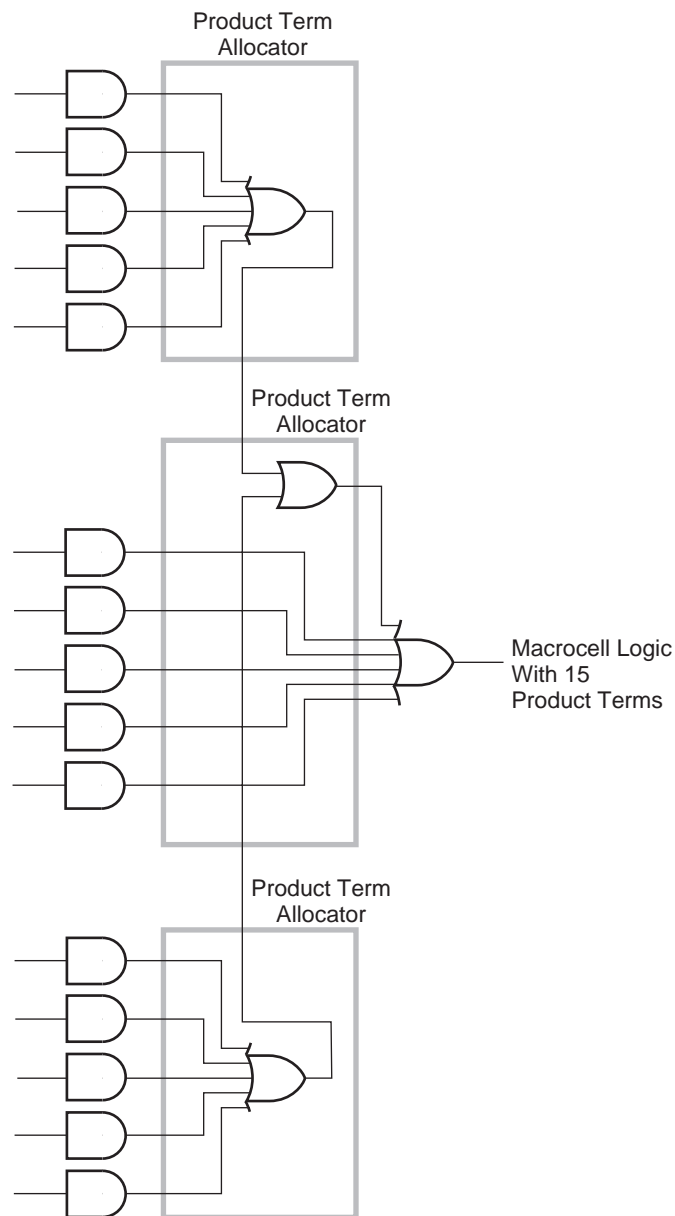
The product term allocator controls how the five direct product terms are assigned to each macrocell. For example, all five direct terms can drive the OR function as shown in **Figure 5**.



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Figure 5: Macrocell Logic Using Direct Product Term

The product term allocator can re-assign other product terms within the FB to increase the logic capacity of a macrocell beyond five direct terms. Any macrocell requiring additional product terms can access uncommitted product terms in other macrocells within the FB. Up to 15 product terms can be available to a single macrocell with only a small incremental delay of t_{PTA} , as shown in **Figure 6**.



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Figure 6: Product Term Allocation With 15 Product Terms

The product term allocator can re-assign product terms from any macrocell within the FB by combining partial sums of products over several macrocells, as shown in **Figure 7**. In this example, the incremental delay is only $2 \cdot T_{PTA}$. All 90 product terms are available to any macrocell, with a maximum incremental delay of $8 \cdot T_{PTA}$.

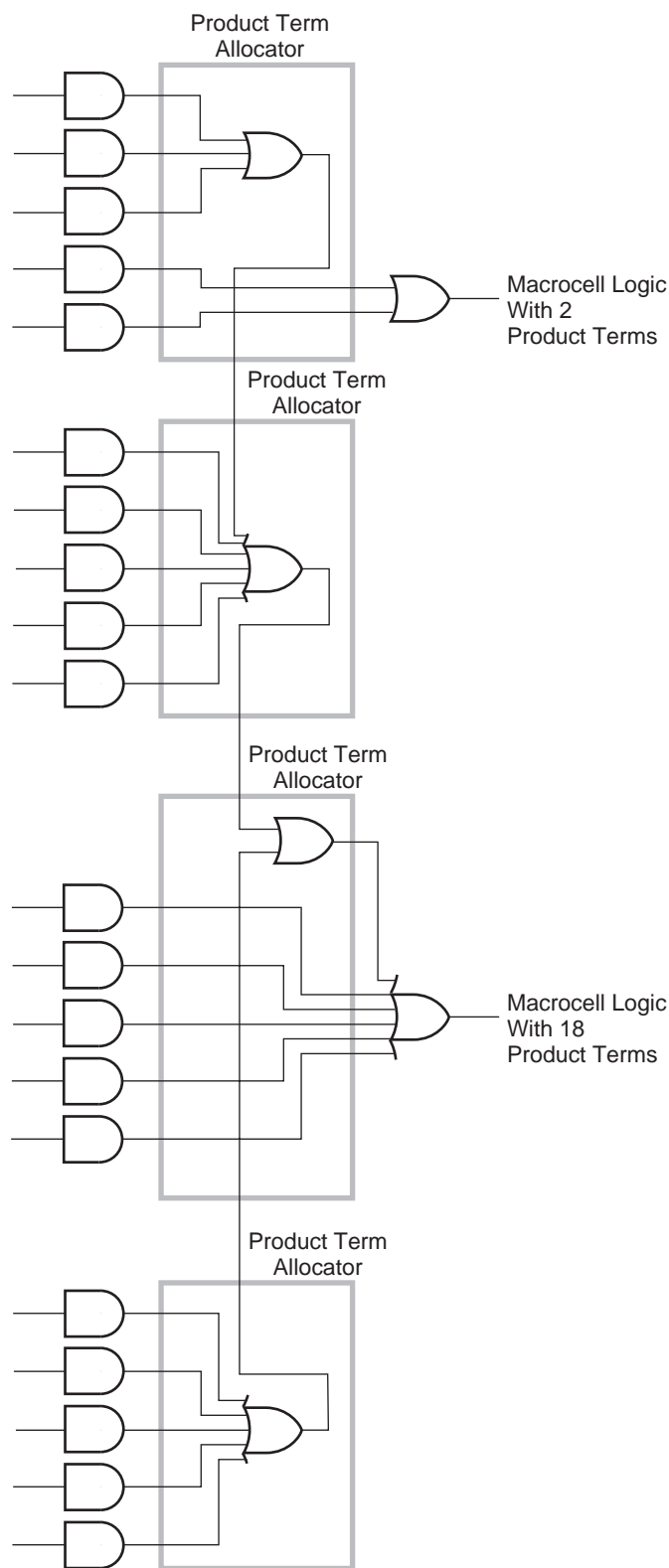
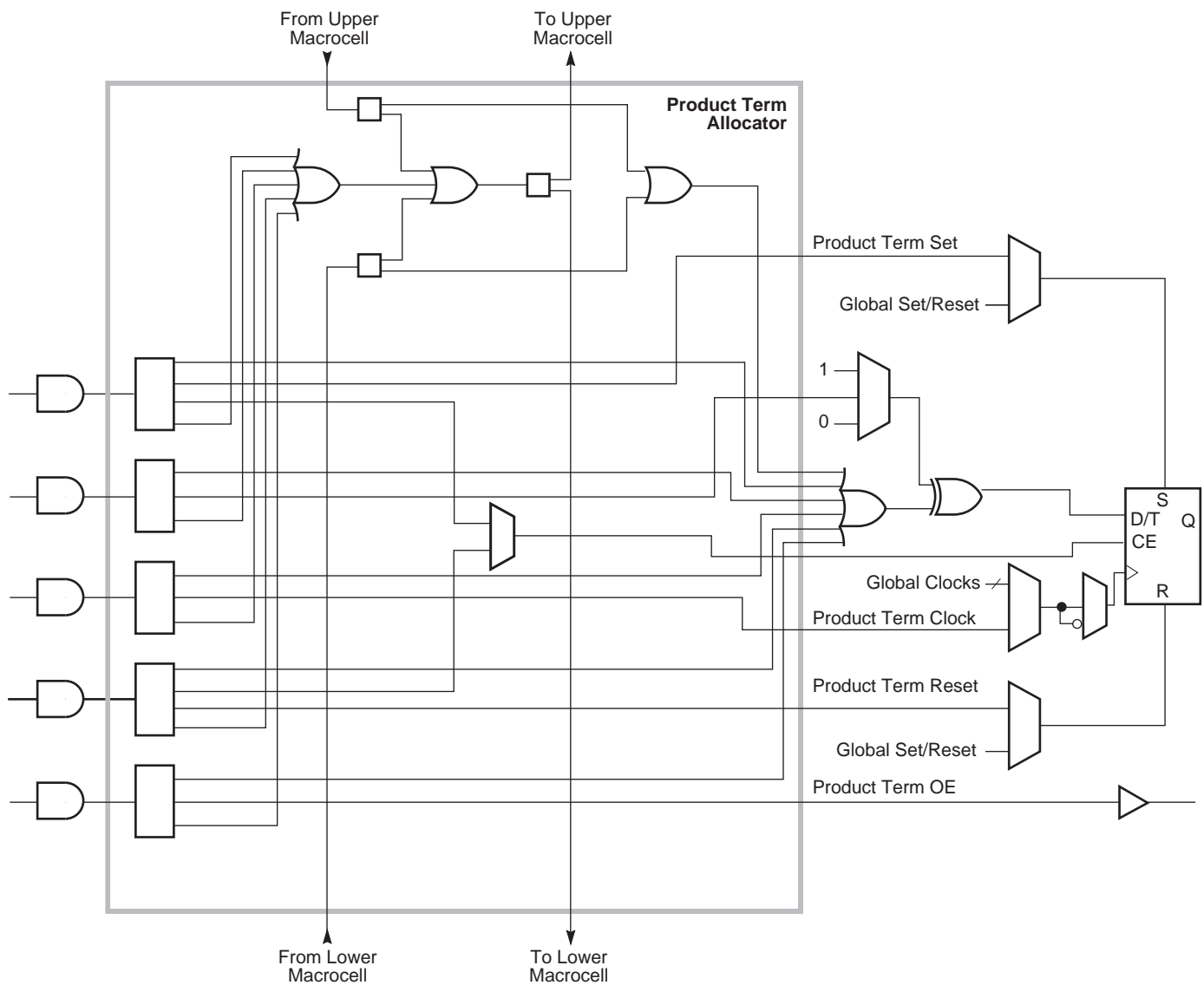


Figure 7: Product Term Allocation Over Several Macrocells

The internal logic of the product term allocator is shown in **Figure 8**.



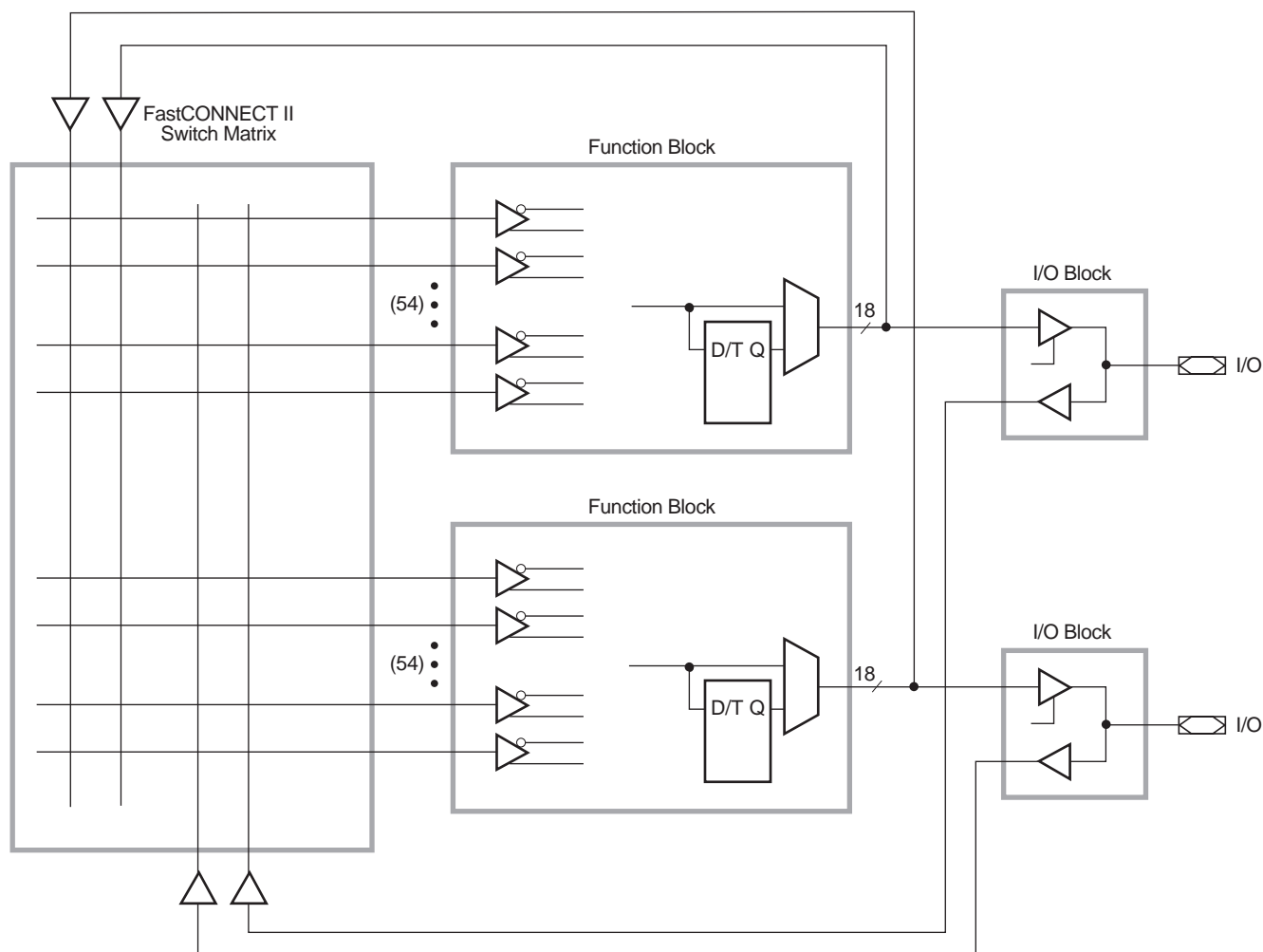
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Figure 8: Product Term Allocator Logic

FastCONNECT II Switch Matrix

The FastCONNECT II Switch Matrix connects signals to the FB inputs, as shown in Figure 9. All IOB outputs (corre-

sponding to user pin inputs) and all FB outputs drive the FastCONNECT II matrix. Any of these (up to a fan-in limit of 54) may be selected to drive each FB with a uniform delay.



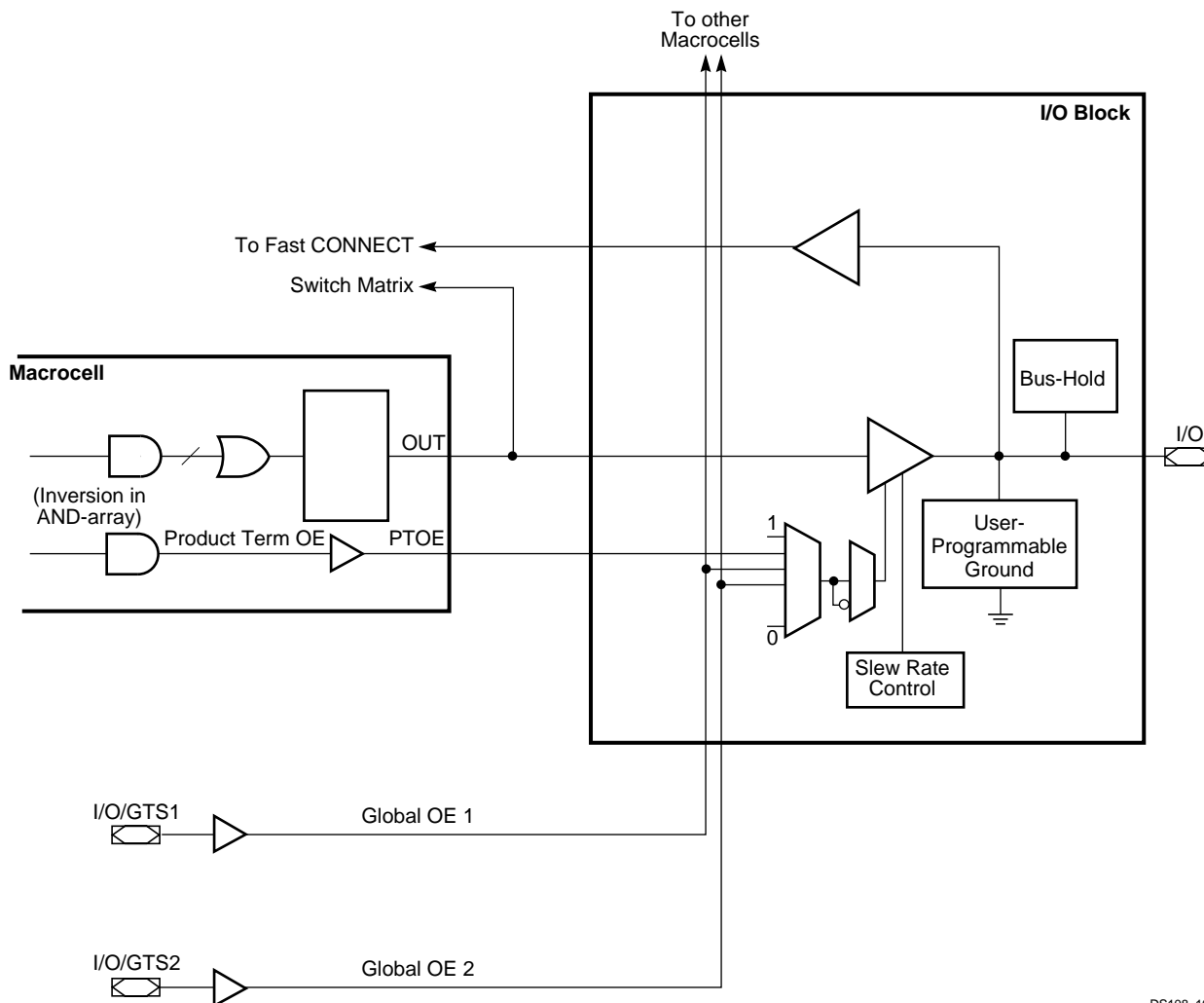
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Figure 9: FastCONNECT II Switch Matrix

I/O Block

The I/O Block (IOB) interfaces between the internal logic and the device user I/O pins. Each IOB includes an input

buffer, output driver, output enable selection multiplexer, and user programmable ground control. See [Figure 10](#) for details.



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Figure 10: I/O Block and Output Enable Capability

The input buffer is compatible with 5V CMOS, 5V TTL, 3.3V CMOS, and 2.5V CMOS signals. The input buffer uses the internal 3.3V voltage supply (V_{CCINT}) to ensure that the input thresholds are constant and do not vary with the V_{CCIO} voltage. Each input buffer provides input hysteresis (50 mV typical) to help reduce system noise for input signals with slow rise or fall edges.

Each output driver is designed to provide fast switching with minimal power noise. All output drivers in the device may be configured for driving either 3.3V CMOS levels (which are compatible with 5V TTL levels as well) or 2.5V CMOS levels by connecting the device output voltage supply (V_{CCIO}) to a 3.3V or 2.5V voltage supply. [Figure 11](#) shows how the XC9500XL device can be used in 3.3V only systems and mixed voltage systems with any combination of 5V, 3.3V and 2.5V power supplies.

Each output driver can also be configured for slew-rate limited operation. Output edge rates may be slowed down to reduce system noise (with an additional time delay of t_{SLEW}) under user control. See [Figure 12](#).

The output enable may be generated from one of four options: a product term signal from the macrocell, any of the global output enable signals (GTS), always "1," or always "0." There are two global output enables for devices with 72 or fewer macrocells, and four global output enables for devices with 144 or more macrocells. Any selected output enable signal may be inverted locally at each pin output to provide maximal design flexibility.

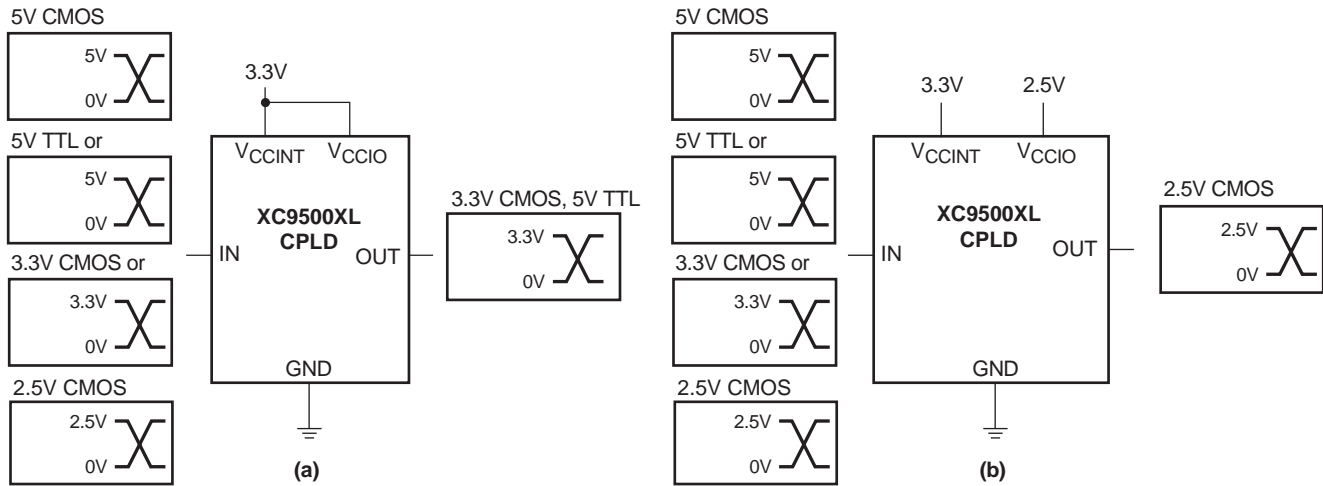
Each IOB provides user programmable ground pin capability. This allows device I/O pins to be configured as additional ground pins in order to force otherwise unused pins to a low voltage state, as well as provide for additional device

grounding capability. This grounding of the pin is achieved by internal logic that forces a logic low output regardless of the internal macrocell signal, so the internal macrocell logic is unaffected by the programmable ground pin capability.

Each IOB also provides for bus-hold circuitry (also called a “keeper”) that is active during valid user operation. The bus-hold feature eliminates the need to tie unused pins either high or low by holding the last known state of the input until the next input signal is present. The bus-hold circuit drives back the same state via a nominal resistance (R_{BH}) of 50k ohms. See [Figure 13](#). Note the bus-hold output will

drive no higher than V_{CCIO} to prevent overdriving signals when interfacing to 2.5V components.

When the device is not in valid user operation, the bus-hold circuit defaults to an equivalent 50k ohm pull-up resistor in order to provide a known repeatable device state. This occurs when the device is in the erased state, in programming mode, in JTAG INTEST mode, or during initial power-up. A pull-down resistor (1k ohm) may be externally added to any pin to override the default R_{BH} resistance to force a low state during power-up or any of these other modes.



DS054_11_042101

Figure 11: XC9500XL Devices in (a) 3.3V only and (b) Mixed 5V/3.3V/2.5V Systems

5V Tolerant I/Os

The I/Os on each XC9500XL device are fully 5V tolerant even though the core power supply is 3.3 volts. This allows 5V CMOS signals to connect directly to the XC9500XL inputs without damage. In addition, the 3.3V V_{CCINT} power supply can be applied before or after 5V signals are applied to the I/Os. In mixed 5V/3.3V/2.5V systems, the user pins, the core power supply (V_{CCINT}), and the output power supply (V_{CCIO}) may have power applied in any order. This makes the XC9500XL devices immune to power supply sequencing problems.

Xilinx proprietary ESD circuitry and high impedance initial state permit hot plugging cards using these devices.

Pin-Locking Capability

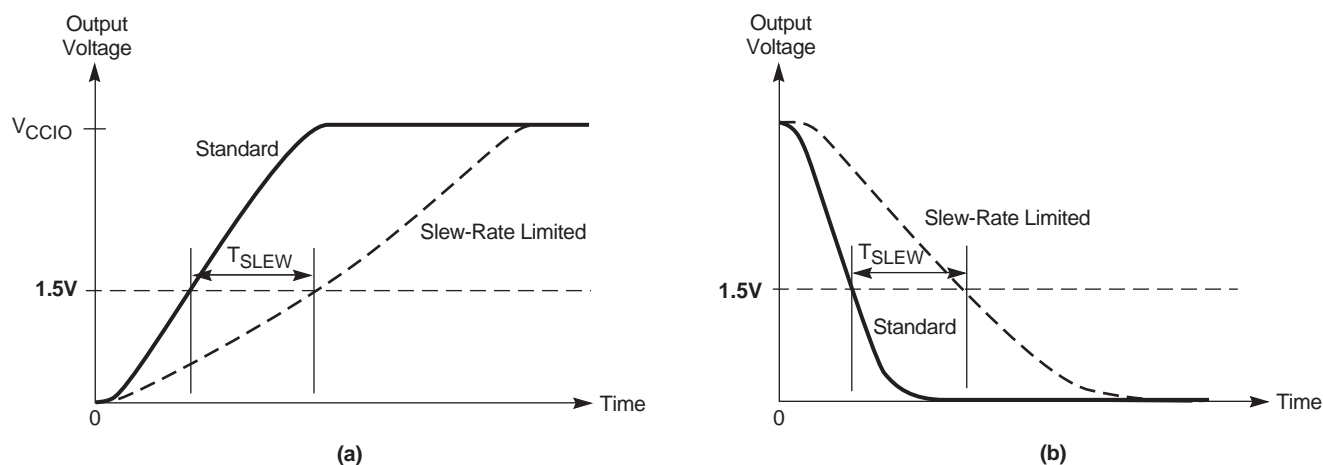
The capability to lock the user defined pin assignments during design iteration depends on the ability of the architec-

ture to adapt to unexpected changes. The XC9500XL devices incorporate architectural features that enhance the ability to accept design changes while maintaining the same pinout.

The XC9500XL architecture provides for superior pin-locking characteristics with a combination of large number of routing switches in the FastCONNECT II switch matrix, a 54-wide input Function Block, and flexible, bi-directional product term allocation within each macrocell. These features address design changes that require adding or changing internal routing, including additional signals into existing equations, or increasing equation complexity, respectively.

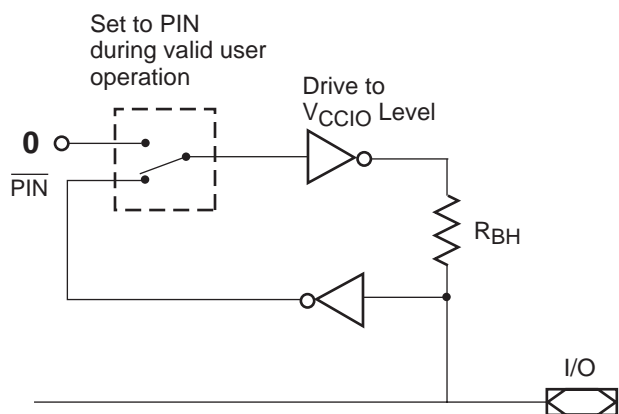
For extensive design changes requiring higher logic capacity than is available in the initially chosen device, the new design may be able to fit into a larger pin-compatible device using the same pin assignments. The same board may be

used with a higher density device without the expense of board rework.



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Figure 12: Output Slew-Rate Control For (a) Rising and (b) Falling Outputs



DS054_13_042101

Figure 13: Bus-Hold Logic

In-System Programming

One or more XC9500XL devices can be daisy chained together and programmed in-system via a standard 4-pin JTAG protocol, as shown in Figure 14. In-system programming offers quick and efficient design iterations and eliminates package handling. The Xilinx development system provides the programming data sequence using a Xilinx download cable, a third-party JTAG development system, JTAG-compatible board tester, or a simple microprocessor interface that emulates the JTAG instruction sequence.

All I/Os are 3-stated and pulled high by the bus-hold circuitry during in-system programming. If a particular signal must remain low during this time, then a pulldown resistor may be added to the pin.

External Programming

XC9500XL devices can also be programmed by the Xilinx HW-130 device programmer as well as third-party programmers. This provides the added flexibility of using pre-programmed devices during manufacturing, with an in-system programmable option for future enhancements and design changes.

Reliability and Endurance

All XC9500XL CPLDs provide a minimum endurance level of 10,000 in-system program/erase cycles and a minimum data retention of 20 years. Each device meets all functional, performance, and data retention specifications within this endurance limit.

IEEE 1149.1 Boundary-Scan (JTAG)

XC9500XL devices fully support IEEE 1149.1 boundary-scan (JTAG). EXTEST, SAMPLE/PRELOAD, BYPASS, USERCODE, INTEST, IDCODE, HIGHZ and CLAMP instructions are supported in each device. Additional instructions are included for in-system programming operations.

Design Security

XC9500XL devices incorporate advanced data security features which fully protect the programming data against unauthorized reading or inadvertent device erasure/reprogramming. Table 3 shows the four different security settings available.

The read security bits can be set by the user to prevent the internal programming pattern from being read or copied. When set, they also inhibit further program operations but

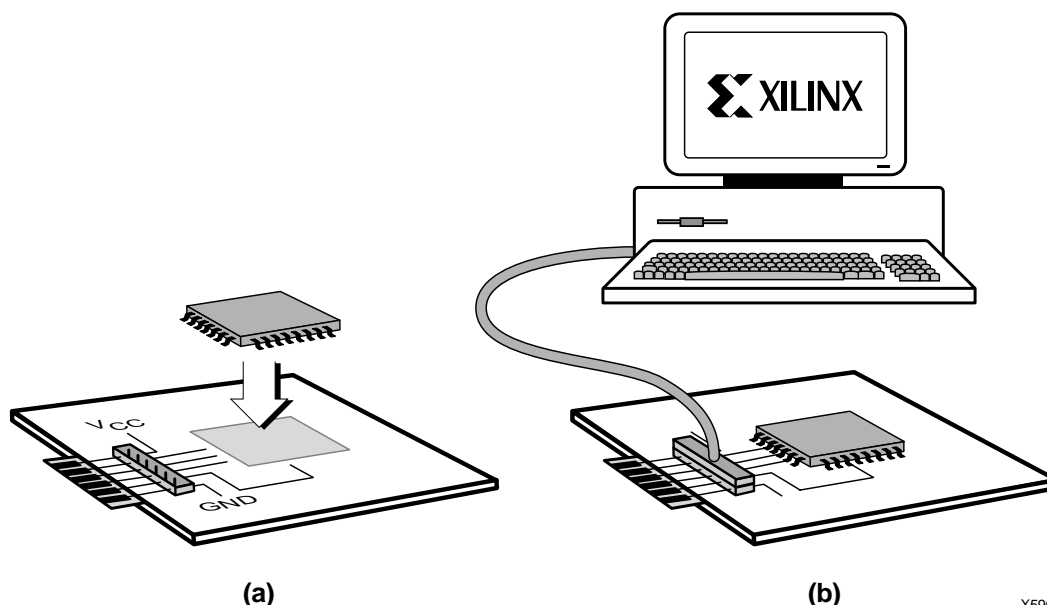
allow device erase. Erasing the entire device is the only way to reset the read security bit.

The write security bits provide added protection against accidental device erasure or reprogramming when the JTAG pins are subject to noise, such as during system power-up. Once set, the write-protection may be deacti-

vated when the device needs to be reprogrammed with a valid pattern with a specific sequence of JTAG instructions.

Table 3: Data Security Options

		Read Security	
		Default	Set
Write Security	Default	Read Allowed Program/Erase Allowed	Read Inhibited Program Inhibited Erase Allowed
	Set	Read Allowed Program/Erase Allowed	Read Inhibited Program/Erase Inhibited



X5902

Figure 14: System Programming Operation (a) Solder Device to PCB and (b) Program Using Download Cable

Low Power Mode

All XC9500XL devices offer a low-power mode for individual macrocells or across all macrocells. This feature allows the device power to be significantly reduced.

Each individual macrocell may be programmed in low-power mode by the user. Performance-critical parts of the application can remain in standard power mode, while other parts of the application may be programmed for low-power operation to reduce the overall power dissipation. Macrocells programmed for low-power mode incur additional delay (t_{LP}) in pin-to-pin combinatorial delay as well as register setup time. Product term clock to output and product term output enable delays are unaffected by the macrocell power-setting.

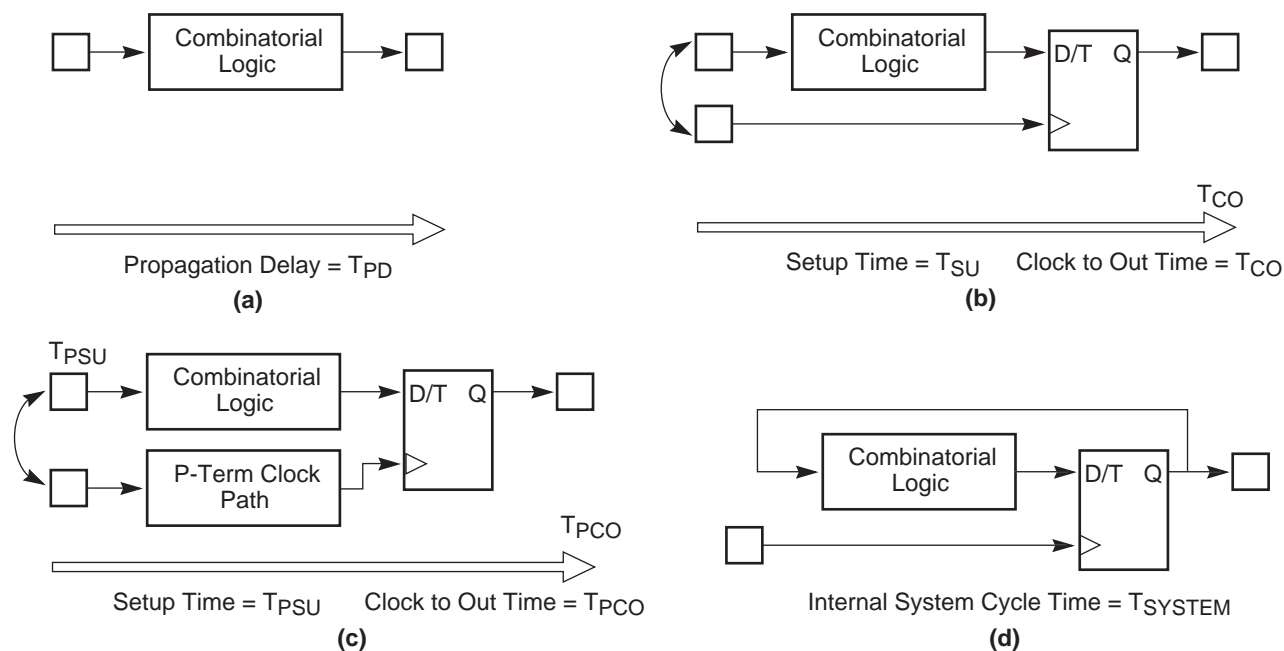
Timing Model

The uniformity of the XC9500XL architecture allows a simplified timing model for the entire device. The basic timing model, shown in Figure 15, is valid for macrocell functions that use the direct product terms only, with standard power setting, and standard slew rate setting. Table 4 shows how each of the key timing parameters is affected by the product term allocator (if needed), low-power setting, and slew-limited setting.

The product term allocation time depends on the logic span of the macrocell function, which is defined as one less than the maximum number of allocators in the product term path. If only direct product terms are used, then the logic span is 0. The example in Figure 6 shows that up to 15 product terms are available with a span of 1. In the case of Figure 7, the 18 product term function has a span of 2.

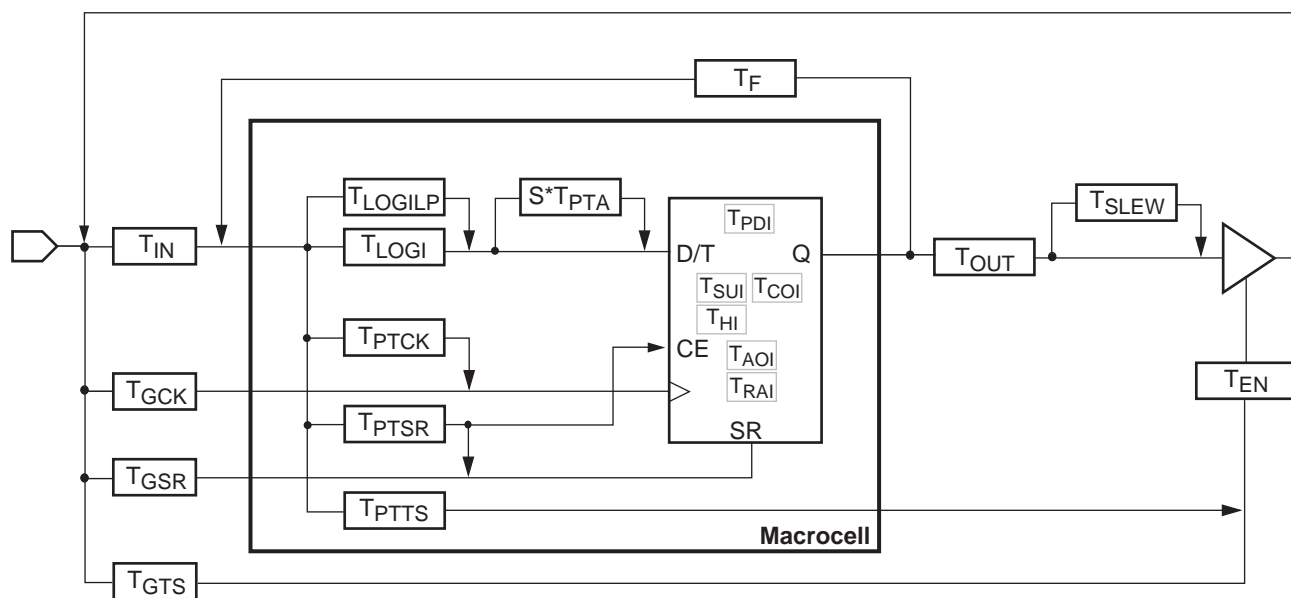
Detailed timing information may be derived from the full timing model shown in Figure 16. The values and explanations

for each parameter are given in the individual device data sheets.



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Figure 15: Basic Timing Model



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Figure 16: Detailed Timing Model

Power-Up Characteristics

The XC9500XL devices are well behaved under all operating conditions. During power-up each XC9500XL device employs internal circuitry which keeps the device in the quiescent state until the V_{CCINT} supply voltage is at a safe level (approximately 2.5V). During this time, all device pins and JTAG pins are disabled and all device outputs are disabled with the pins weakly pulled high, as shown in Table 5. When the supply voltage reaches a safe level, all user registers become initialized (typically within 200 μ s), and the device is immediately available for operation, as shown in Figure 17.

If the device is in the erased state (before any user pattern is programmed), the device outputs remain disabled with weak pull-up. The JTAG pins are enabled to allow the device to be programmed at any time. All devices are shipped in the erased state from the factory.

If the device is programmed, the device inputs and outputs take on their configured states for normal operation. The JTAG pins are enabled to allow device erasure or boundary-scan tests at any time.

Development System Support

The XC9500XL family and associated in-system programming capabilities are fully supported in either software solutions available from Xilinx.

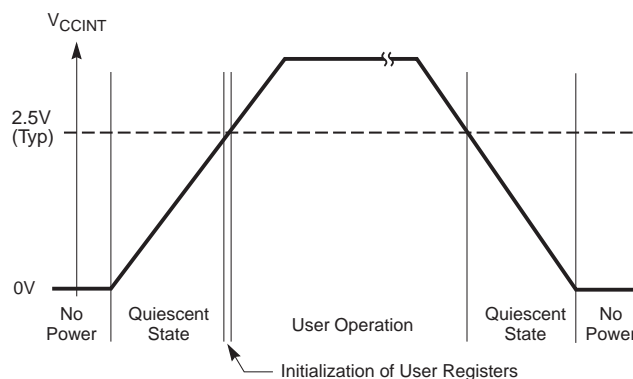
The Foundation Series is an all-in-one development system containing schematic entry, HDL (VHDL, Verilog, and ABEL), and simulation capabilities. It supports the

XC9500XL family as well as other CPLD and FPGA families.

The Alliance Series includes CPLD and FPGA implementation technology as well as all necessary libraries and interfaces for Alliance partner EDA solutions.

FastFLASH Technology

A 0.35 micron feature size CMOS Flash process is used to fabricate all XC9500XL devices. The FastFLASH process provides high performance logic capability, fast programming times, and superior reliability and endurance ratings.



DS054_17_042101

Figure 17: Device Behavior During Power-up

Table 4: Timing Model Parameters

Parameter	Description	Product Term Allocator ⁽¹⁾	Macrocell Low-Power Setting	Output Slew-Limited Setting
T_{PD}	Propagation Delay	$+ T_{PTA} * S$	$+ T_{LP}$	$+ T_{SLEW}$
T_{SU}	Global Clock Setup Time	$+ T_{PTA} * S$	$+ T_{LP}$	-
T_{CO}	Global Clock-to-output	-	-	$+ T_{SLEW}$
T_{PSU}	Product Term Clock Setup Time	$+ T_{PTA} * S$	$+ T_{LP}$	-
T_{PCO}	Product Term Clock-to-output	-	-	$+ T_{SLEW}$
T_{SYSTEM}	Internal System Cycle Period	$+ T_{PTA} * S$	$+ T_{LP}$	-

Notes:

1. S = the logic span of the function, as defined in the text.

Table 5: XC9500XL Device Characteristics

Device Circuitry	Quiescent State	Erased Device Operation	Valid User Operation
IOB Bus-Hold	Pull-up	Pull-up	Bus-Hold
Device Outputs	Disabled	Disabled	As Configured
Device Inputs and Clocks	Disabled	Disabled	As Configured
Function Block	Disabled	Disabled	As Configured
JTAG Controller	Disabled	Enabled	Enabled

Absolute Maximum Ratings⁽¹⁾

Symbol	Description	Min.	Max.	Units
V_{CC}	Supply voltage relative to GND	-0.5	4.0	V
V_{IN}	Input voltage relative to GND ⁽²⁾	-0.5	5.5	V
V_{TS}	Voltage applied to 3-state output ⁽²⁾	-0.5	5.5	V
T_{STG}	Storage temperature (ambient)	-65	+150	°C
T_J	Junction temperature	-	+150	°C

Notes:

- Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those listed under Operating Conditions is not implied. Exposure to Absolute Maximum Ratings conditions for extended periods of time may affect device reliability.
- Maximum DC undershoot below GND must be limited to either 0.5V or 10 mA, whichever is easier to achieve. During transitions, the device pins may undershoot to -2.0 V or overshoot to +7.0V, provided this over- or undershoot lasts less than 10 ns and with the forcing current being limited to 200 mA.
- For soldering guidelines, see the Package Information on the Xilinx website.

Recommended Operating Conditions

Symbol	Parameter	Min	Max	Units
T_A	Ambient temperature	-40	+125	°C
V_{CCINT}	Supply voltage for internal logic and input buffers	3.0	3.6	V
V_{CCIO}	Supply voltage for output drivers for 3.3V operation	3.0	3.6	V
	Supply voltage for output drivers for 2.5V operation	2.3	2.7	V
V_{IL}	Low-level input voltage	0	0.80	V
V_{IH}	High-level input voltage	2.0	5.5	V
V_O	Output voltage	0	V_{CCIO}	V

Quality and Reliability Characteristics

Symbol	Parameter	Min	Max	Units
T_{DR}	Data Retention	20	-	Years
N_{PE}	Program/Erase Cycles (Endurance)	10,000	-	Cycles

DC Characteristic Over Recommended Operating Conditions

Symbol	Parameter	Test Conditions		Min	Max	Units
V _{OH}	Output high voltage for 3.3V outputs	I _{OH} = −4.0 mA		2.4	-	V
	Output high voltage for 2.5V outputs	I _{OH} = −500 μA		90% V _{CCIO}	-	V
V _{OL}	Output low voltage for 3.3V outputs	I _{OL} = 8.0 mA		-	0.4	V
	Output low voltage for 2.5V outputs	I _{OL} = 500 μA		-	0.4	V
I _{IL}	Input leakage current	V _{CC} = Max, V _{IN} = GND or V _{CC}		-	±10	μA
I _{IH}	I/O high-Z leakage current	V _{CC} = Max, V _{IN} = GND or V _{CC}		-	±10	μA
C _{IN}	I/O capacitance	V _{IN} = GND, f = 1.0 MHz		-	10	pF
I _{CC}	Operating supply current (low power mode, active)	V _I = GND, No load f = 1.0 MHz	XC9536XL	10 (Typical)		mA
			XC9572XL	20 (Typical)		mA

Power Estimation

Power dissipation in CPLDs can vary substantially depending on the system frequency, design application and output loading. To help reduce power dissipation, each macrocell in a XC9500XL device may be configured for low-power mode (from the default high-performance mode). In addition, unused product-terms and macrocells are automatically deactivated by the software to further conserve power.

For a general estimate of I_{CC} , the following equation may be used:

$$I_{CC}(mA) = MC_{HS}(0.175 \cdot PT_{HS} + 0.345) + MC_{LP}(0.052 \cdot PT_{LP} + 0.272) + 0.04 \cdot MC_{TOG}(MC_{HS} + MC_{LP}) \cdot f$$

where:

MC_{HS} = # macrocells in high-speed configuration

PT_{HS} = average number of high-speed product terms per macrocell

MC_{LP} = # macrocells in low power configuration

PT_{LP} = average number of low power product terms per macrocell

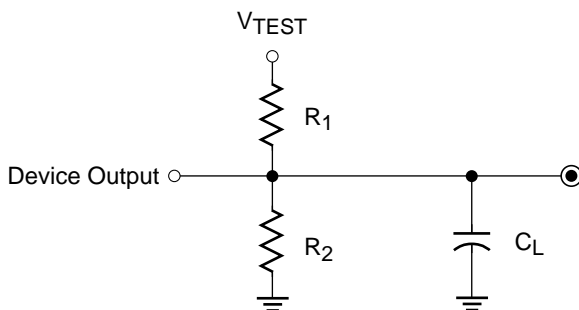
f = maximum clock frequency

$MCTOG$ = average % of flip-flops toggling per clock (~12%)

This calculation was derived from laboratory measurements of an XC9500XL part filled with 16-bit counters and allowing a single output (the LSB) to be enabled. The actual I_{CC} value varies with the design application and should be verified during normal system operation.

AC Characteristics

Symbol	Parameter	-10		Units
		Min	Max	
T_{PD}	I/O to output valid	-	10.0	ns
T_{SU}	I/O setup time before GCK	6.5	-	ns
T_H	I/O hold time after GCK	0	-	ns
T_{CO}	GCK to output valid	-	5.8	ns
f_{SYSTEM}	Multiple FB internal operating frequency	-	100.0	MHz
T_{PSU}	I/O setup time before p-term clock input	2.1	-	ns
T_{PH}	I/O hold time after p-term clock input	4.4	-	ns
T_{PCO}	P-term clock output valid	-	10.2	ns
T_{OE}	GTS to output valid	-	7.0	ns
T_{OD}	GTS to output disable	-	7.0	ns
T_{POE}	Product term OE to output enabled	-	11.0	ns
T_{POD}	Product term OE to output disabled	-	11.0	ns
T_{AO}	GSR to output valid	-	14.5	ns
T_{PAO}	P-term S/R to output valid	-	15.3	ns
T_{WLH}	GCK pulse width (High or Low)	4.5	-	ns
T_{PLH}	P-term clock pulse width (High or Low)	7.0	-	ns



Output Type	VCCIO	VTEST	R1	R2	CL
	3.3V	3.3V	320 Ω	360 Ω	35 pF
	2.5V	2.5V	250 Ω	660 Ω	35 pF

DS058_03_081500

Figure 18: AC Load Circuit

Internal Timing Parameters

Symbol	Parameter	-10		Units
		Min	Max	
Buffer Delays				
T _{IN}	Input buffer delay	-	3.5	ns
T _{GCK}	GCK buffer delay	-	1.8	ns
T _{GSR}	GSR buffer delay	-	4.5	ns
T _{GTS}	GTS buffer delay	-	7.0	ns
T _{OUT}	Output buffer delay	-	3.0	ns
T _{EN}	Output buffer enable/disable delay	-	0	ns
Product Term Control Delays				
T _{PTCK}	Product term clock delay	-	2.7	ns
T _{PTSR}	Product term set/reset delay	-	1.8	ns
T _{PTTS}	Product term 3-state delay	-	7.5	ns
Internal Register and Combinatorial Delays				
T _{PDI}	Combinatorial logic propagation delay	-	1.7	ns
T _{SUI}	Register setup time	3.0	-	ns
T _{HI}	Register hold time	3.5	-	ns
T _{ECSU}	Register clock enable setup time	3.0	-	ns
T _{ECHO}	Register clock enable hold time	3.5	-	ns
T _{COI}	Register clock to output valid time	-	1.0	ns
T _{AOI}	Register async. S/R to output delay	-	7.0	ns
T _{RAI}	Register async. S/R recover before clock	10.0		ns
T _{LOGI}	Internal logic delay	-	1.8	ns
T _{LOGILP}	Internal low power logic delay	-	7.3	ns
Feedback Delays				
T _F	Fast CONNECT II feedback delay	-	4.2	ns
Time Adders				
T _{PTA}	Incremental product term allocator delay	-	1.0	ns
T _{SLEW}	Slew-rate limited delay	-	4.5	ns

XC9536XL I/O Pins

Function Block	Macro-cell	VQ44	VQ64	BScan Order	Function Block	Macro-cell	VQ44	VQ64	BScan Order
1	1	40	9	105	2	1	39	8	51
1	2	41	10	102	2	2	38	7	48
1	3	43 ⁽¹⁾	15 ⁽¹⁾	99	2	3	36 ⁽¹⁾	5 ⁽¹⁾	45
1	4	42	11	96	2	4	37	6	42
1	5	44 ⁽¹⁾	16 ⁽¹⁾	93	2	5	34 ⁽¹⁾	2 ⁽¹⁾	39
1	6	2	19	90	2	6	33 ⁽¹⁾	64 ⁽¹⁾	36
1	7	1 ⁽¹⁾	17 ⁽¹⁾	87	2	7	32	63	33
1	8	3	20	84	2	8	31	62	30
1	9	5	22	81	2	9	30	61	27
1	10	6	24	78	2	10	29	60	24
1	11	7	25	75	2	11	28	57	21
1	12	8	27	72	2	12	27	56	18
1	13	12	33	69	2	13	23	50	15
1	14	13	35	66	2	14	22	48	12
1	15	14	36	63	2	15	21	45	9
1	16	16	38	60	2	16	20	44	6
1	17	18	42	57	2	17	19	43	3
1	18	-	39	54	2	18	-	49	0

Notes:

1. Global control pin.

XC9536XL Global, JTAG and Power Pins

Pin Type	VQ44	VQ64
I/O/GCK1	43	15
I/O/GCK2	44	16
I/O/GCK3	1	17
I/O/GTS1	36	5
I/O/GTS2	34	2
I/O/GSR	33	64
TCK	11	30
TDI	9	28
TDO	24	53
TMS	10	29
V _{CCINT} 3.3V	15, 35	3, 37
V _{CCIO} 2.5V/3.3V	26	55
GND	4, 17, 25	21, 41, 54
No Connects	-	1, 4, 12, 13, 14, 18, 23, 26, 31, 32, 34, 40, 46, 47, 51, 52, 58, 59

XC9572XL I/O Pins

Function Block	Macrocell	VQ64	TQ100	BScan Order
1	1	-	16	213
1	2	8	13	210
1	3	12	18	207
1	4	13	20	204
1	5	9	14	201
1	6	10	15	198
1	7	-	25	195
1	8	11	17	192
1	9	15 ⁽¹⁾	22 ⁽¹⁾	189
1	10	18	28	186
1	11	16 ⁽¹⁾	23 ⁽¹⁾	183
1	12	23	33	180
1	13	-	36	177
1	14	17 ⁽¹⁾	27 ⁽¹⁾	174
1	15	19	29	171
1	16	-	39	168
1	17	20	30	165
1	18	-	40	162
2	1	-	87	159
2	2	60	94	156
2	3	58	91	153
2	4	59	93	150
2	5	61	95	147
2	6	62	96	144
2	7	-	3 ⁽²⁾	141
2	8	63	97	138
2	9	64 ⁽¹⁾	99 ⁽¹⁾	135
2	10	1	1	132
2	11	2 ⁽¹⁾	4 ⁽¹⁾	129
2	12	4	6	126
2	13	-	8	123
2	14	5 ⁽³⁾	9 ⁽³⁾	120
2	15	6	11	117
2	16	-	10	114
2	17	7	12	111
2	18	-	92	108

Function Block	Macrocell	VQ64	TQ100	BScan Order
3	1	-	41	105
3	2	22	32	102
3	3	31	49	99
3	4	32	50	96
3	5	24	35	93
3	6	34	53	90
3	7	-	54	87
3	8	25	37	84
3	9	27	42	81
3	10	39	60	78
3	11	33	52	75
3	12	40	61	72
3	13	-	63	69
3	14	35	55	66
3	15	36	56	63
3	16	42	64	60
3	17	38	58	57
3	18	-	59	54
4	1	-	65	51
4	2	43	67	48
4	3	46	71	45
4	4	47	72	42
4	5	44	68	39
4	6	49	76	36
4	7	-	77	33
4	8	45	70	30
4	9	-	66	27
4	10	51	81	24
4	11	48	74	21
4	12	52	82	18
4	13	-	85	15
4	14	50	78	12
4	15	56	89	9
4	16	-	86	6
4	17	57	90	3
4	18	-	79	0

Notes:

1. Global control pin.
2. GTS1 for TQ100.
3. GTS1 VQ64.

XC9572XL Global, JTAG and Power Pins

Pin Type	VQ64	TQ100
I/O/GCK1	15	22
I/O/GCK2	16	23
I/O/GCK3	17	27
I/O/GTS1	5	3
I/O/GTS2	2	4
I/O/GSR	64	99
TCK	30	48
TDI	28	45
TDO	53	83
TMS	29	47
V _{CCINT} 3.3V	3, 37	5, 57, 98
V _{CCIO} 2.5V/3.3V	26, 55	26, 38, 51, 88
GND	14, 21, 41, 54	21, 31, 44, 62, 69, 75, 84, 100
No Connects	-	2, 7, 19, 24, 34, 43, 46, 73, 80

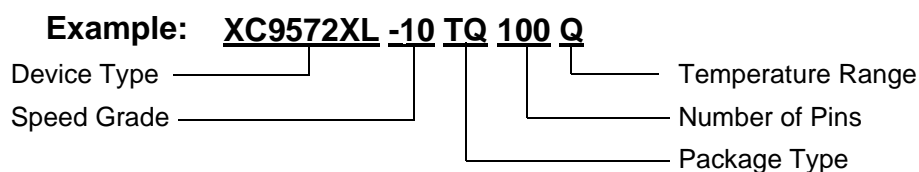
Component Availability

Pins		44	64	100
Type		Plastic VQFP	Plastic VQFP	Plastic TQFP
Code		VQ44	VQ64	TQ100
XC9536XL	-10	Q	Q	-
XC9572XL	-10	-	Q	Q

Notes:

- Q = Automotive IQ (T_A = -40°C to +125°C).

Ordering Information



Device Ordering Options

Device	Speed		Package		Temperature
XC9536XL	-10	10 ns pin-to-pin delay	VQ44	44-pin Quad Flat Pack (VQFP)	Q = Automotive IQ T _A = -40°C to +125°C
XC9572XL			VQ64	64-pin Quad Flat Pack (VQFP)	
			TQ100	100-pin Thin Quad Flat Pack (TQFP)	

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
06/17/02	1.0	Initial Xilinx release